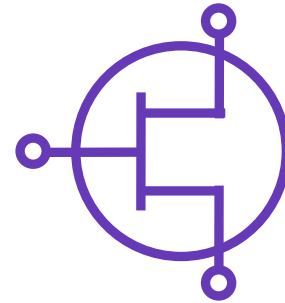


Model Features

- Broadband (DC to 40 GHz)
- Large-signal model (Modelithics-Enhanced Angelov)
- Measurement Validations:
 - Pulsed I-V (25 C to 85 C)
 - Multi-bias S-parameters (25 C to 85 C)
 - Load pull (25 C), 12 and 18 GHz
 - IP3 linearity validation, 12 GHz, 7 V 60%*I*_{DSS}
- Advanced model feature: enabling intrinsic I-V sensing.



MES-MWT-MWT3F-001
MwT-3F
Discrete GaAs MESFET

Model Description

The MES-MWT-MWT3F-001 is a non-linear model for the MwT-3F a discrete 300 um GaAs MESFET (additional information is available at www.mwtinc.com). The model is based on the extraction of a customized Angelov non-linear model that is validated against the following Modelithics measurement data: I-V, S-parameters, load pull and IP3.

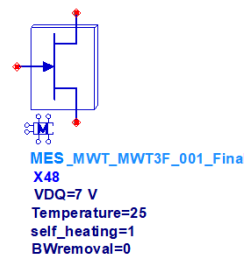
Technical Notes

- Model is optimized for 2, 4 and 7 V operation (26 mA (30% *I*_{DSS}), 44 mA (50% *I*_{DSS}) and 52 mA (60% *I*_{DSS}).
- Model Parameters:
 - **VDSQ**: For setting the optimum bias point of the model (default=7 V).
 - **Temperature**: represents the backside ambient temperature, validated at 25 C and 85 C.
 - **Self_heat**: switch for the electrothermal model (0 or 1), 0= self-heating is turned off, 1 (default)= self-heating is turned on.
 - **BWremoval**: 0 includes wire assembly (only used in measurements, 1 (default) sets model reference planes at the center of the gate, drain, and source bond pads.
 - [Modelithics Micro Probe Accessories](#) part number 0503, 5 mil Alumina adapter substrates were used to access the bond pads of discrete die.

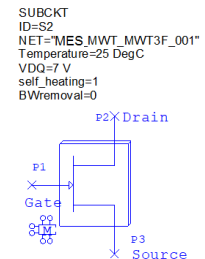
Model Simulation Settings

- **I-V**: self_heat: 0 for I-V simulations (self heating model turned OFF), Temperature=25 C
- **S-Parameters**: self_heat: 1 for CW bias, Temperature=25 C
- **Load Pull Single-tone and two tone validations**: self_heat: 1 for CW bias; Temperature=25 C.

Model Representation

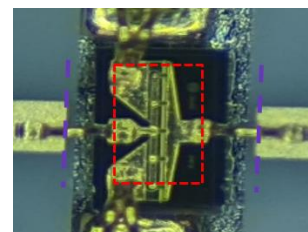


Keysight ADS



NI AWR

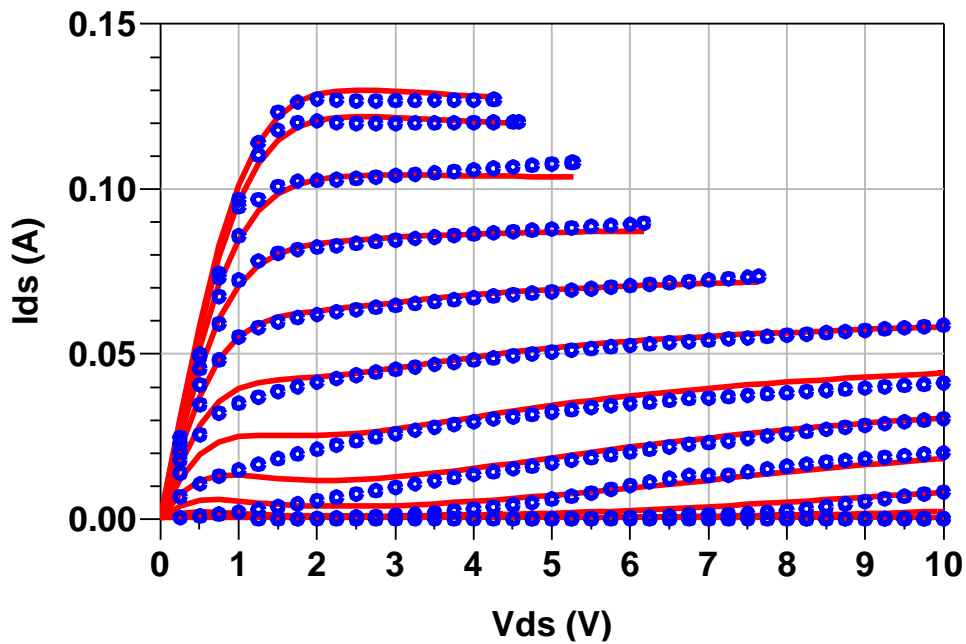
Reference Planes



Model and Measurement Reference Planes (BWremoval=1)

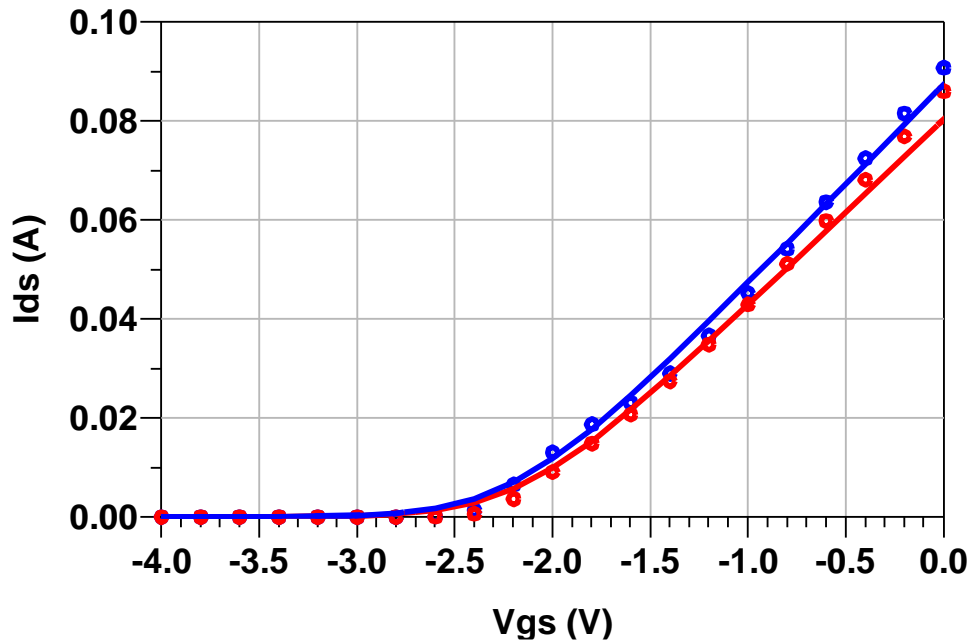
Model and Measurement Reference Planes (BWremoval=0)

DC I-V Characteristics: $V_{DSQ} = 7\text{ V}$, 25 C



Legend: Red Solid lines - Model data, O Symbols - Measured data
 Simulated at 25 C with V_{GS} varying from -4 to 1 V in steps of 0.4 V,
 V_{DS} varying from 0 to 10 V in steps of 0.25 V. Model self_heat = 0.

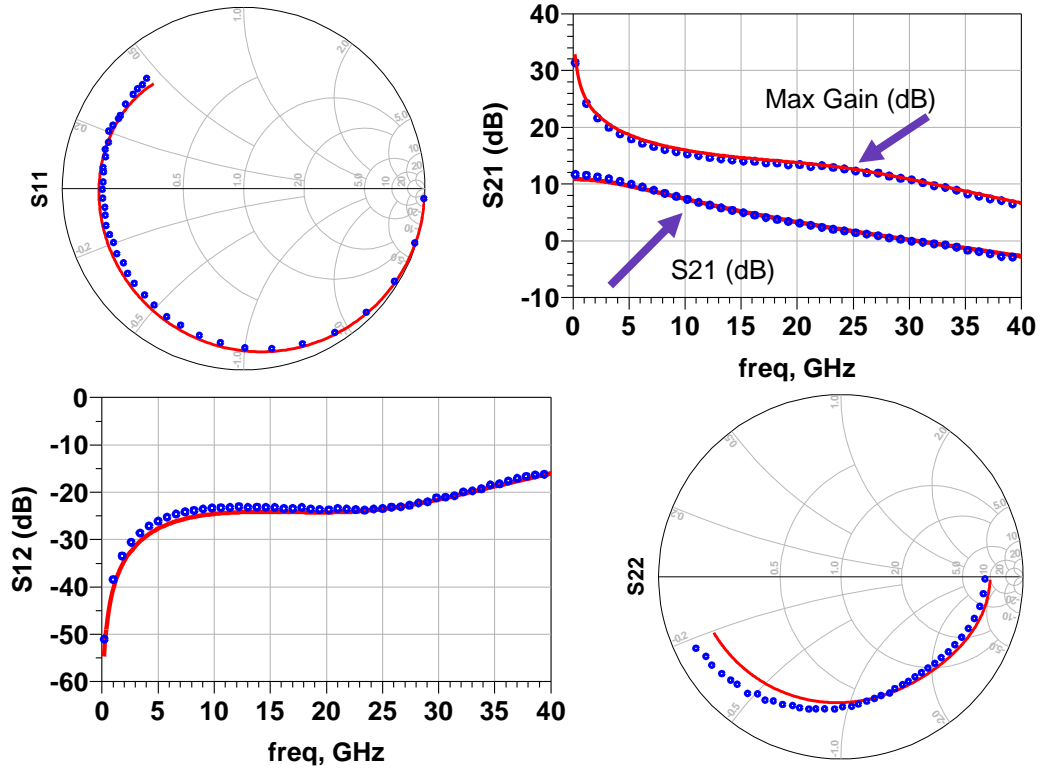
Model vs. Measurement Temperature IV Characteristics



Legend: Red Solid lines: 85 C, Blue Solid lines: 25 C.
 Solid lines - Model data, Symbols - Measured data
 Simulated at 25 C and 85 C, V_{DSQ} of 7 V. Model self_heat = 0.

S-Parameters Model vs. Measured:

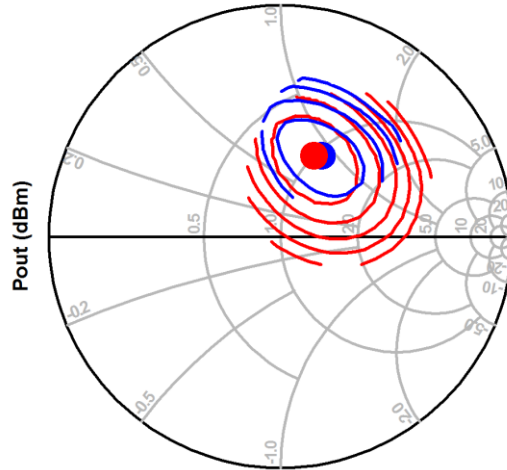
VDS = 7 V, VGS = -0.81 V, IDS = 52.2 mA (60% IDSS), 25 C



Legend: Red Solid lines - Model data, O Symbols - Measured data
 Simulated at 25 C with the frequency range from 0.2 – 40 GHz. 50 Ω Smith Charts
 BWremoval = 0

Load Pull Validation: Frequency = 12 GHz
 VDS = 7 V, VGS = -0.81 V, IDS = 52.2 mA (60% IDSS),
 Input Power = 11 dBm, Z0 = 50 Ω Center, 25 C

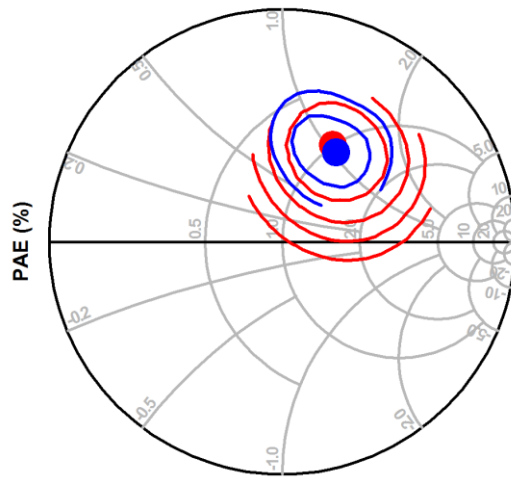
Power Tuning (0.5 dB contour step)



Test Bench Impedances (Ohms):

- ZS = 9.9 + j*20.7
- ZS2 = 97.2 - j*14.4
- ZS3 = 81.9 - j*13.8
- ZLoad2 = 45.9 - j*19.1
- ZLoad3 = 16.9 + j*14.4

Efficiency Tuning (5% contour step)



Legend: Red Solid lines – Model, Blue Solid lines – Measured, BWremoval = 0

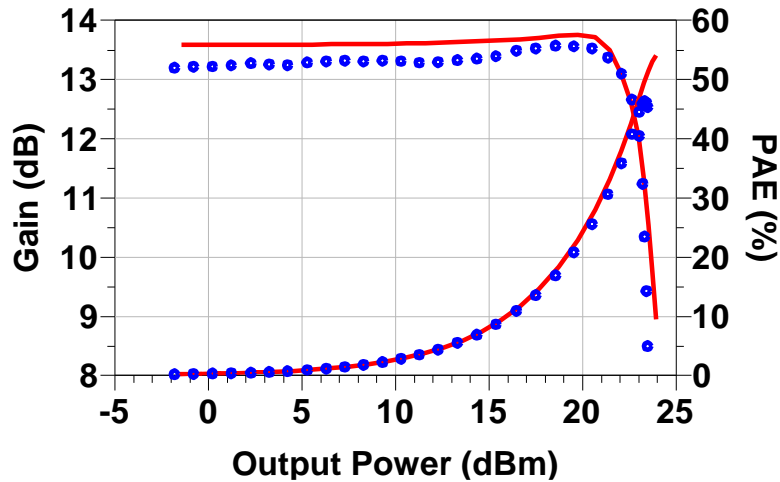
Load Pull Summary	Max Power Load Impedance (Ohms)	Max Power Value (dBm)	Max PAE Load Impedance (Ohms)	Max PAE Value (%)
Measured	53.0 + j*43.8	23.0	53.8 + j*52.1	44.9
Model	50.0 + j*41.0	23.2	49.4 + j*53.0	48.2

Load pull data has been processed for contour display

Single Tone Power Sweep: Frequency = 12 GHz
 VDS = 7 V, VGS = -0.81 V, IDS = 52.2 mA (60% IDSS), 25 C

Load Condition: Measured Power Tuned

Transducer Gain and Power Added Efficiency (PAE)



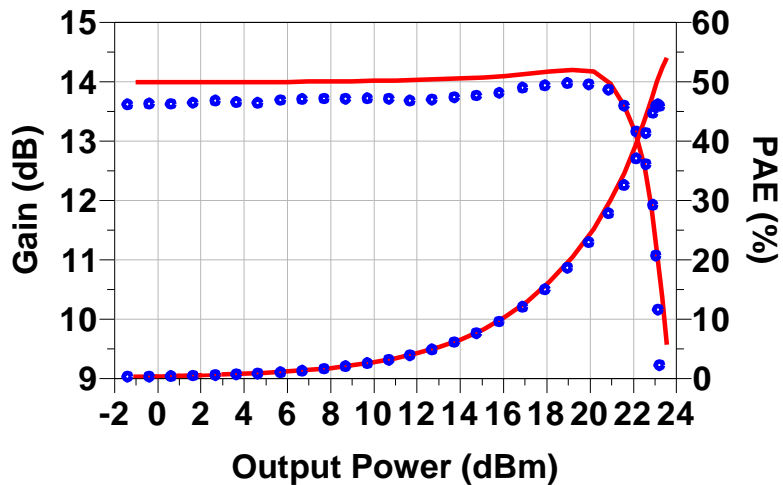
Load Condition: Power Tuned
 Test Bench Impedances
 (Ohms):

- ZS = 9.9 + j*20.7
- ZS2 = 97.2 - j*14.4
- ZS3 = 81.9 - j*13.8
- ZLoad = 53.0 + j*43.8
- ZLoad2 = 59.1 + j*1.0
- ZLoad3 = 31.2 + j*1.2

Legend: Red Solid lines - Model data, O Symbols - Measured data, BWremoval = 0

Load Condition: Measured PAE Tuned

Transducer Gain and Power Added Efficiency (PAE)

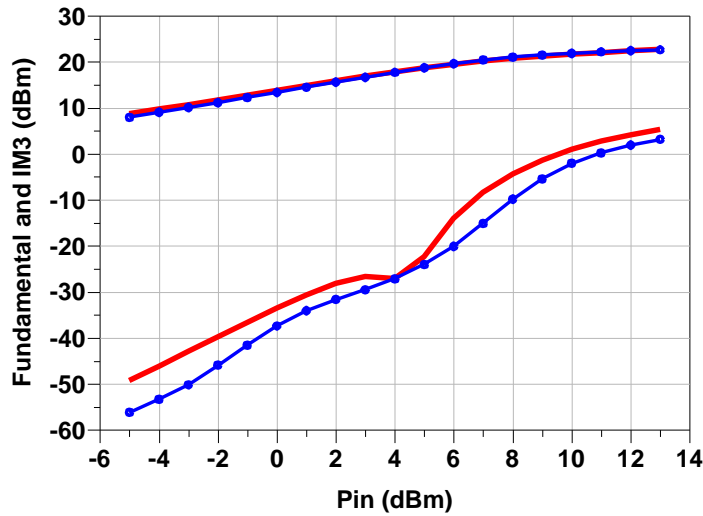


Load Condition: PAE Tuned
 Test Bench Impedances
 (Ohms):

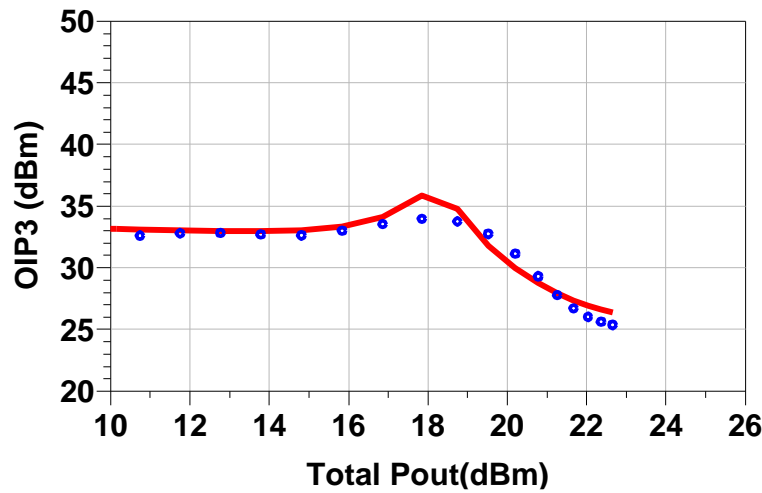
- ZS = 9.9 + j*20.7
- ZS2 = 97.2 - j*14.4
- ZS3 = 81.9 - j*13.8
- ZLoad = 53.8 + j*52.1
- ZLoad2 = 59.7 - j*2.0
- ZLoad3 = 27.2 + j*7.1

Legend: Red Solid lines - Model data, O Symbols - Measured data, BWremoval = 0

Two Tone Validation 12 GHz



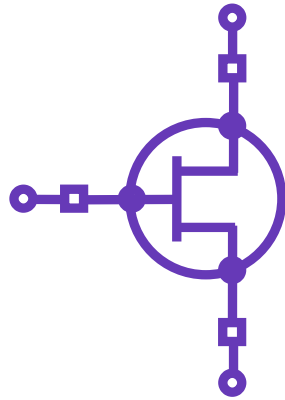
Simulated (solid line) and measured (symbols) tuned for max Power.
 Source impedance = $(10.5 + j*21.3)$ Ohms, load impedance = $(49.4 + j*44.6)$ Ohms.
 Frequency = 12 GHz, 5 MHz tone spacing, Vds = 7 V, 52.2 mA (60%Idss)



Simulated (solid line) and measured (symbols) tuned for max Power.
 Source impedance = $(10.5 + j*21.3)$ Ohms, load impedance = $(49.4 + j*44.6)$ Ohms.
 Frequency = 12 GHz, 5 MHz tone spacing, Vds = 7 V, 52.2 mA (60%Idss)

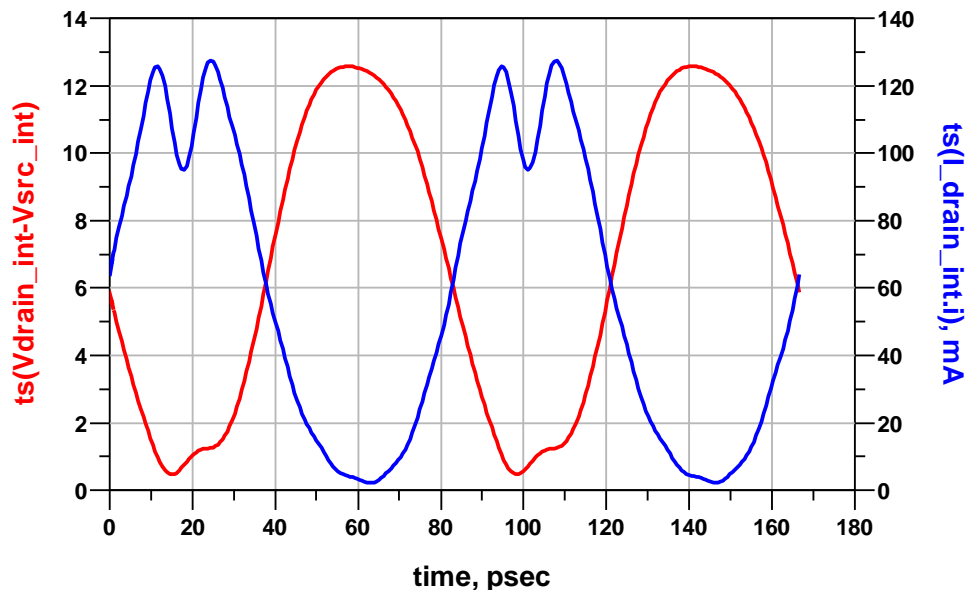
Advanced Model Features: Intrinsic Voltage/Current Sensing

Get V_{ds} and I_{ds} model data near current generator intrinsic planes while tuning.



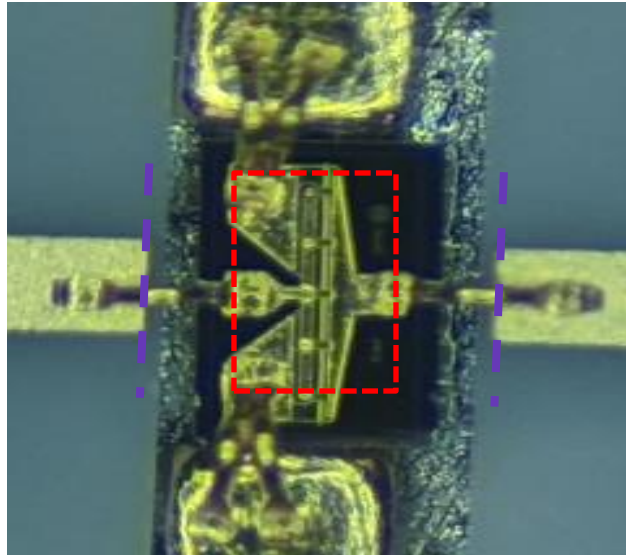
- External Model Planes
- Internal Model Planes for I/V waveform analysis
- Parasitic networks available separately from intrinsic I/V model

Example Plot of internal node I_{ds} and V_{ds}



Results based on harmonic balance simulation at 19 dBm input power, PAE matched at 12 GHz, 7 V, and 52.2 mA. $Z_S = (9.9 + j*20.7)$ Ohms, $Z_{S2} = (97.2 - j*14.4)$ Ohms, $Z_{S3} = (81.9 - j*13.8)$ Ohms, $Z_{Load} = (53.0 + j*43.8)$ Ohms, $Z_{Load2} = (59.1 + j*1.0)$ Ohms, $Z_{Load3} = (31.2 + j*1.2)$ Ohms.

Assembly Diagram



Test fixture details:

[Modelithics Micro Probe Accessories](#) part number 0503, 5 mil Alumina adapter substrates were used to access the bond pads of discrete die.

- Device thickness: 3.93 mil
- Test board thickness: 5 mil
- Bond-wire diameter: 1 mil gold
- Gate and Drain single bond-wire length: 6 mil +/-2 (average)
- Source bond-wire length (two wires per source pad): 6 mil +/-2 (average)
- Metal standoff external next to each source pad is 4 mil thick, its purpose is to shorten the bondwire lengths to the source/ground.
- Blue line is model planes with bondwires ON (BWremoval=0)
- Red line is model planes with bondwires OFF (BWremoval=1)

Model and Datasheet Revision Notes

03/07/2023	Original model and datasheet development
06/21/2023	Datasheet updated with IP3 validation